



Product/Process Change Notice - PCN 10_0150 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Wafer Bumping Changes at STATSchipPAC Singapore for AD53559 and ADATE30X

Publication Date: 28-Oct-2010

Effectivity Date: 28-Apr-2011 (the earliest date that a customer could expect to receive changed material)

Revision Description:

Adding ADATE302_02 part number

Description Of Change

Wafer bumping material changes at STATSchipPAC Singapore for AD53559 and ADATE30X are as follows:

Flip Chip Bump on Die

From a Sn63/Pb37 bump; To a Sn96.5/Ag3.0/Cu0.5 Pb-free bump composition

Bump Process

From stencil printing; To preformed solder ball attach

Substrate Core Material

From CCL-HL-832; To DS-7409HGB

Substrate Prepreg Material

From GHPL-830HS; To DS-7409HG

Solder Mask Material

From PSR_4000_AUS-303; To PSR_4000_AUS-308

Reason For Change

STATSchipPAC has announced they are obsoleting Pb-bearing solder paste. In order to maintain continuity of supply, ADI is converting to Pb-free and Halogen free package materials. These materials have equivalent or improved properties and are not at risk to ongoing Environmental Legislation. ADI products using Pb-free bump alloys including Sn, Ag and Cu are mature.

Impact of the change (positive or negative) on fit, form, function & reliability

This change will not affect fit, form, function & reliability.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary

ADI_PCN_10_0150_Rev_A_Qual Plan Summary .pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan:

PCN_Japan@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (6)

| | | | | | |
|-------------------------|-----------------------------|-------------------------|-----------------------------|-------------------------|-------------------------|
| AD53559 / AD53559-02BBC | AD53559 / AD53559-02BBC-RL7 | AD53559 / AD53559-05BBC | AD53559 / AD53559-05BBC-RL7 | ADATE304 / ADATE304BBCZ | ADATE306 / ADATE306BBCZ |
|-------------------------|-----------------------------|-------------------------|-----------------------------|-------------------------|-------------------------|

Added Parts On This Revision - Product Family / Model Number (1)

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| ADATE302-02 / ADATE302-02BBCZ |
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Appendix B - Revision History

| Rev | Publish Date | Rev Description |
|------------|---------------------|--------------------------------|
| Rev. - | 30-Sep-2010 | Initial Release |
| Rev. A | 28-Oct-2010 | Adding ADATE302_02 part number |

Analog Devices, Inc.

DocId:1363 Parent DocId:None Layout Rev.4